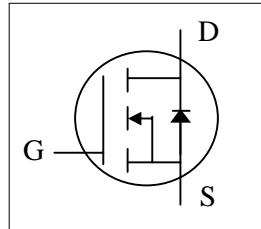
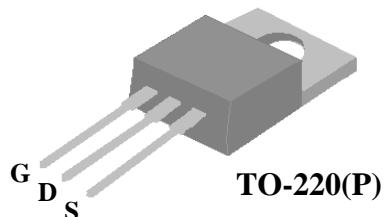




- ▼ Low Gate Charge
- ▼ Single Drive Requirement
- ▼ Fast Switching Performance
- ▼ RoHS Compliant & Halogen-Free



$BV_{DSS}$	60V
$R_{DS(ON)}$	16mΩ
$I_D$	60A



## Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 package is widely preferred for commercial-industrial applications and suited for low voltage applications.

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	+25	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	60	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	38	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	240	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	89	W
	Linear Derating Factor	0.7	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Value	Units
$R_{thj-c}$	Maximum Thermal Resistance, Junction-case	1.4	°C/W
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient	62	°C/W



# AP9972AGP-HF

## Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=250\mu\text{A}$	60	-	-	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=1\text{mA}$	-	0.06	-	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_{\text{D}}=30\text{A}$	-	-	16	$\text{m}\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$ , $I_{\text{D}}=250\mu\text{A}$	2	-	4	V
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_{\text{D}}=40\text{A}$	-	44	-	S
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	10	$\text{uA}$
	Drain-Source Leakage Current ( $T_j=125^\circ\text{C}$ )	$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$	-	-	250	$\text{uA}$
$I_{\text{GSS}}$	Gate-Source Leakage	$V_{\text{GS}}=\pm 25\text{V}$ , $V_{\text{DS}}=0\text{V}$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_{\text{D}}=40\text{A}$	-	49	80	nC
$Q_{\text{gs}}$	Gate-Source Charge		-	13	-	nC
$Q_{\text{gd}}$	Gate-Drain ("Miller") Charge		-	20	-	nC
$t_{\text{d}(\text{on})}$	Turn-on Delay Time <sup>2</sup>	$V_{\text{DS}}=30\text{V}$ $I_{\text{D}}=40\text{A}$	-	14	-	ns
$t_r$	Rise Time		-	80	-	ns
$t_{\text{d}(\text{off})}$	Turn-off Delay Time		-	27	-	ns
$t_f$	Fall Time		-	57	-	ns
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	2410	3860	pF
$C_{\text{oss}}$	Output Capacitance		-	290	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	240	-	pF
$R_g$	Gate Resistance	f=1.0MHz	-	2	3	$\Omega$

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{\text{SD}}$	Forward On Voltage <sup>2</sup>	$I_{\text{S}}=40\text{A}$ , $V_{\text{GS}}=0\text{V}$	-	-	1.3	V
$t_{\text{rr}}$	Reverse Recovery Time <sup>2</sup>	$I_{\text{S}}=30\text{A}$ , $V_{\text{GS}}=0\text{V}$ ,	-	48	-	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$dI/dt=100\text{A}/\mu\text{s}$	-	75	-	nC

## Notes:

1.Pulse width limited by Max. junction temperature.

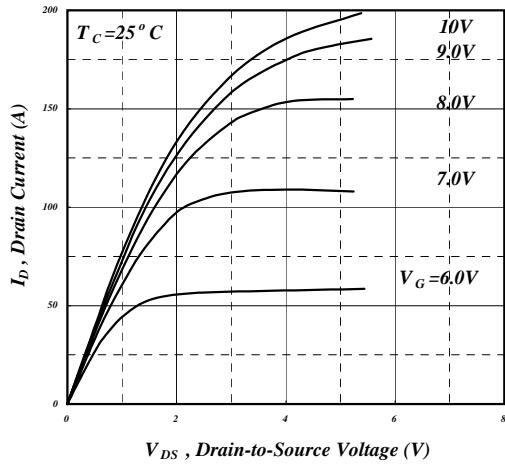
2.Pulse test

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

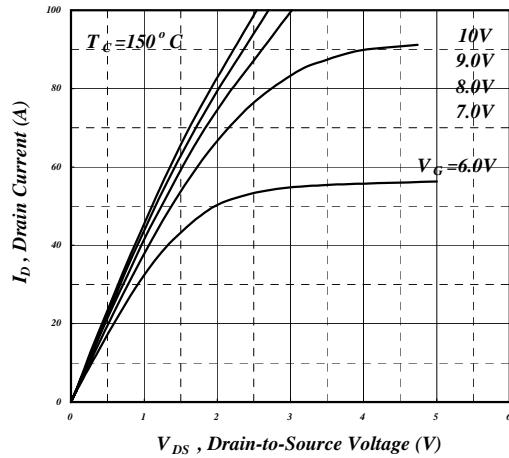
USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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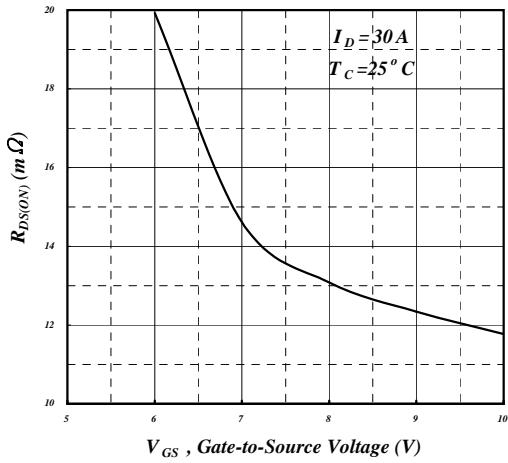
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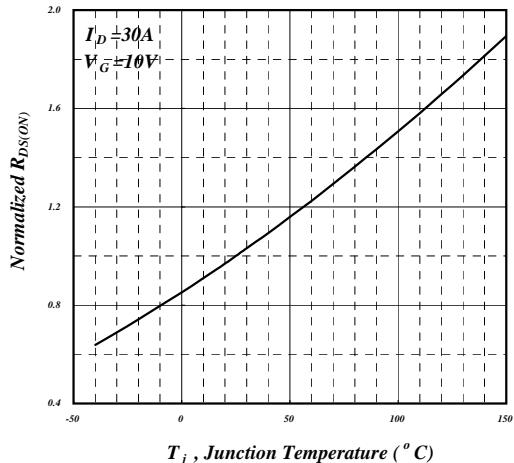
**Fig 1. Typical Output Characteristics**



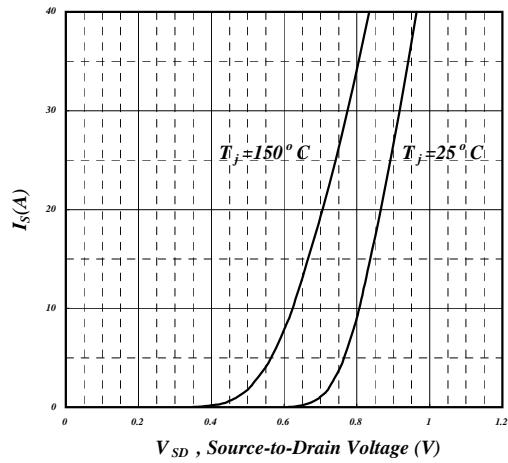
**Fig 2. Typical Output Characteristics**



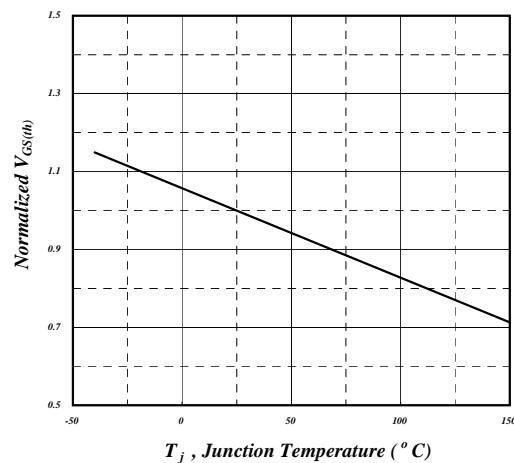
**Fig 3. On-Resistance v.s. Gate Voltage**



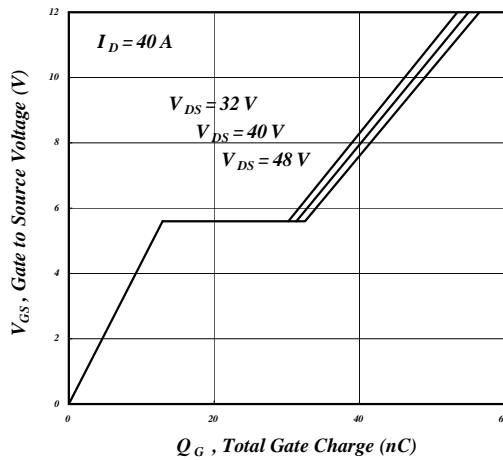
**Fig 4. Normalized On-Resistance v.s. Junction Temperature**



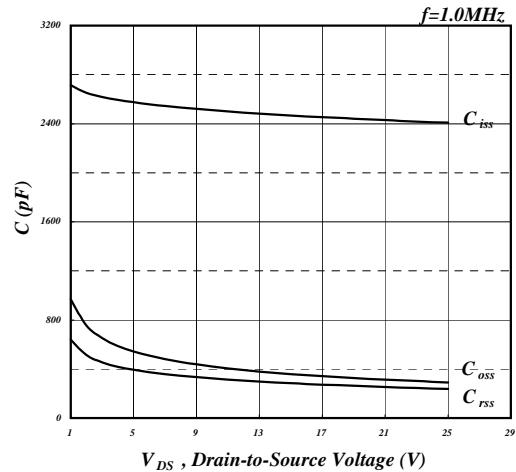
**Fig 5. Forward Characteristic of Reverse Diode**



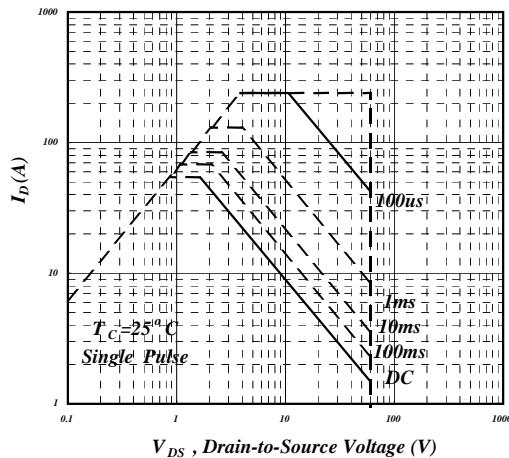
**Fig 6. Gate Threshold Voltage v.s. Junction Temperature**



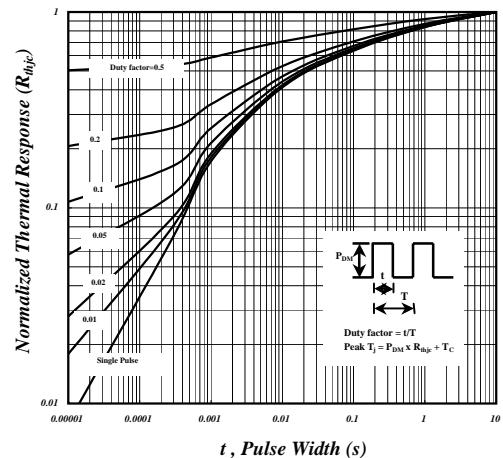
**Fig 7. Gate Charge Characteristics**



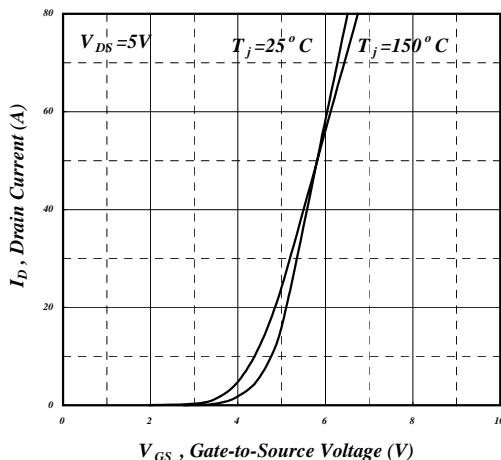
**Fig 8. Typical Capacitance Characteristics**



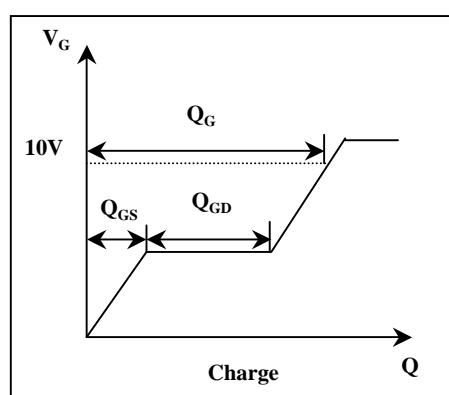
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



**Fig 11. Transfer Characteristics**



**Fig 12. Gate Charge Waveform**